

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **05/31/2022**

Details for "LM2676T-12/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM2676T-12/NOPB	SN	Level-1-NA-UNLIM	Texas Instruments Electronics	NDZ 7	14.99 x 10.16 x 4.57	2549.7

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.000001	0.000166	2	0	0
Copper and Its Alloys	Copper	7440-50-8	0.601306	99.997173	999972	0.023583	236
Copper and Its Alloys	Iron	7439-89-6	0.000003	0.000499	5	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000002	0.000333	3	0	0
Precious Metals	Silver	7440-22-4	0.000011	0.001829	18	0	0
Sub-Total			0.601323	100	1000000	0.023584	236
Die Attach Adhesive							
Other Nonferrous Metals and Alloys	Antimony	7440-36-0	0.174503	10.000006	100000	0.006844	68
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.134269	65.000009	650000	0.044486	445
Precious Metals	Silver	7440-22-4	0.436257	24.999986	250000	0.017111	171
Sub-Total			1.745029	100	1000000	0.068441	684
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1184.888686	99.709568	997096	46.471819	464718
Copper and Its Alloys	Phosphorus	7723-14-0	0.071204	0.005992	60	0.002793	28
Copper and Its Alloys	Tin	7440-31-5	1.780111	0.149798	1498	0.069817	698
Precious Metals	Silver	7440-22-4	1.6	0.134642	1346	0.062753	628
Sub-Total			1188.34	100	1000000	46.607181	466072
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	2.9	13.06895	130689	0.113739	1137
Other Nonferrous Metals and Alloys	Tin	7440-31-5	19.29	86.93105	869311	0.756562	7566
Sub-Total			22.19	100	1000000	0.870301	8703
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	1182.30195	89	890000	46.370366	463704
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	39.852875	3	30000	1.563046	15630
Thermoplastics	Epoxy	85954-11-6	106.274333	8	80000	4.168123	41681
Sub-Total			1328.429158	100	1000000	52.101535	521015
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	8.387435	100	1000000	0.328959	3290
Sub-Total			8.387435	100	1000000	0.328959	3290
Total			2549.692945			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.